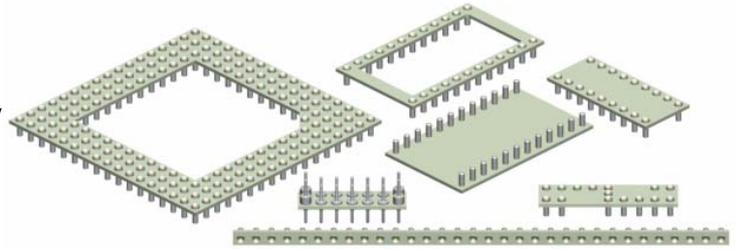


E-tec's super low profile sockets and adapters are designed for use in applications where height above board is most critical.

The sockets have a profile of 0,60mm above board and they can be combined with the adapters to achieve a board to board interconnection height of 2,20mm max.

Also available in this socket range are the ultra low profile SMT sockets with a height above board of only 3,45mm.



Super Low Profile Sockets						Super Low Profile Adapters	
SMT use			through hole use				
<b>Terminal style</b>	DIM "A"	DIM "B"	DIM "C"	DIM "D"	DIM "E"	<p><b>Style 377</b></p>	
<b>144</b>	3,45/.136	3,05/.120	0,94/.037	0,45/.018	1,15/.045		

Specifications			
<b>Mechanical data</b>		<b>Electrical data</b>	
Force per contact (avg)	0,70N insertion / 0,25N extraction	Breakdown voltage at 60 Hz	500 V AC
Contact life	>50 cycles min.	Contact resistance at 1A	4,3 mΩ typ
Solderability	as per IEC 60068-2-58	Insulation resistance	5 × 10 <sup>9</sup> Ω min.
<b>Material</b>		Current rating	1A max., 100V
Terminal (RoHS compliant)	BeCu	Capacitance	2 pF max.
Insulator (RoHS compliant)	Glass Epoxy FR4	<b>Operating temperature</b>	
		-55 °C to +125 °C	

### How to order

XXX - x x x - E x x x (- x x X) - x x (/x)

Series	DIP spacing	Nbr of contacts	Terminal styles	Plating	Pitch
<b>LSP</b> = DIP sockets <b>SSP</b> = SIP sockets <b>DSP</b> = 2-row SIP's <b>PGS</b> = PGA sockets <b>ZZS</b> = Zig-Zag sockets	see pages for LSP series: for SSP series: for DSP series: for ZZS series:	POS SIB/SIS DIS ZZP	See drawings above for 2,54mm and 2,00mm pitch.  For 1,27mm pitch please contact nearest sales office.	- <b>95</b> = tin/gold (tin leadfree) (not available for adapter terminals) - <b>55</b> = gold/gold - <b>99</b> = tin/tin (leadfree)	Complete with <b>1</b> = 1,27mm <b>2</b> = 2,00mm 2.54mm pitch is standard. Others available on request

### Grid size & Configuration code only for PGA sockets

Please refer to PGA socket pages 29 to 31